ABBOCIATION CONNECTING LECTRANICS INDUSTRIES® Material Composition © Copyright 2005. IPC. international and Pan-A	Bannockt	ourn, Illinois. A	Il rights reserved untions.		This docume level parts, t	ent is a declar he declaration	ation of th	e substances sses all lowe	within the 1 r level mate	nanufacturer lis rials for which t	ted item. the manut	Note: if th facturer ha	e item is an as s engineering	ssembly with lowe responsibility.		
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					nd Mfg In	formation				
Supplier Information																
Company name* Company univ			nique ID Ur			Unique ID Authority					Response Date*					
onsemi										202	2024-04-20					
Contact Name Title - Contact				Phone - Contact*			Em	Email - Contact*								
Product-Env-Stewards Product Enviro Co				Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			sentative	P		Phone - Representative*				Em	Email - Representative*					
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Pro	Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item	n Number Mfr Item Name				Effective Da			ng Site	Weig	;ht*	UOM	Unit Type			
	Drivers with E		Dual 5 A High Sp Drivers with Enab (AECQ100 Grade	le for Automotiv						22.59		mg	Each			
Manufacturing Proccess Informatio	n															
Terminal Plating / Grid Array Mater	Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy J	STD-020 MSL Rating		Peak Pr	Peak Process Body Temperature		re Max Tir	Max Time at Peak Temperature		Number of Reflow Cycles				
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	1			260		C	C 30		seconds					
Comments																
evel 1 - maximum time at peak temperature	during so	dering is 10-3	0 seconds													
or more information regarding material co	nposition	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.01	mg	Supplier	Silicon (Si)	7440-21-3		1.01	mg
Die Attach	0.18	mg	Supplier	Silver (Ag)	7440-22-4		0.135	mg
			Supplier	Epoxy resins	129915-35-1		0.045	mg
Lead Frame	8.04	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0121	mg
			Supplier	Silicon (Si)	7440-21-3		0.0523	mg
			В	Nickel (Ni)	7440-02-0		0.2412	mg
			Supplier	Copper (Cu)	7440-50-8		7.7345	mg
Mold Compound-Black	13.13	mg		Epoxy resin	proprietary data		0.6565	mg
			Supplier	Phenolic Resin	Proprietary Data		0.6565	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.2626	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0657	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.4887	mg
Plating	0.15	mg	Supplier	Palladium (Pd)	7440-05-3		0.0093	mg
			В	Nickel (Ni)	7440-02-0		0.1391	mg
			Supplier	Gold (Au)	7440-57-5		0.0016	mg
Wire Bond	0.08	mg	Supplier	Palladium (Pd)	7440-05-3		0.0008	mg
			Supplier	Copper (Cu)	7440-50-8		0.0792	mg